

Migrating to Infineon S29GL-P Flash Family from Numonyx 130 nm Embedded Flash Memory (J3)/130 nm StrataFlash® Embedded Memory (P30) Devices

About this document

Scope and purpose

This application note provides conversion guidelines to Infineon S29GL-P flash family devices from Numonyx Embedded Memory (J3) and Numonyx StrataFlash® Embedded Memory (P30) devices.

Table of contents

About this document	1
Table of contents	1
1 Introduction	2
2 Feature Comparison	3
3 Security Feature	5
4 Package and Pinout	6
4.1 56 Pin TSOP Pinout Comparison	6
4.2 BGA Pinout Comparisons	7
4.3 Infineon 64-ball Fortified BGA Pinout vs. J3 Easy BGA Pinout.....	7
4.4 Infineon 64-ball Fortified BGA Pinout vs. P30 Easy BGA Pinout	8
5 Software Support	10
Revision history	11

Introduction

1 Introduction

This application note provides conversion guidelines to Infineon S29GL-P flash family devices from Numonyx Embedded Memory (J3) and Numonyx StrataFlash® Embedded Memory (P30) devices.

This application note is based on information available to date from data sheets and other application notes publicly available from both Infineon and Numonyx. There may be specification updates that are not incorporated in this document. Please verify all relevant specifications (i.e. Data Sheets and Specification Bulletins) before finalizing any designs.

Feature Comparison

2 Feature Comparison

Infineon flash family devices are 3.0 V single power ($V_{CC} = 2.7\text{-}3.6\text{V}$) flash memory manufactured using 90 nm MirrorBit™ technology. The S29GL-P product family includes densities from 128 Mb to 1 Gb.

Key attributes of Infineon S29GL-P products are

- Ease-of-Use: Seamless package and pinout transition between densities.
- High Performance: Fast Read, Program and Erase times.
- Advanced Sector Protection: Robust security feature allows for complete and total control of security levels for each and every sector.
- Enhanced Versatile I/O™: Wide I/O voltage range from 1.65V to 3.6V to support various applications.

Table 1 Feature Comparisons between Infineon S29GL-P Flash Family and Numonyx Embedded Flash Memory (J3 – 130 nm)

Feature		Product Specification			
		Infineon S29GL-P Flash Family		Numonyx Embedded Flash Memory (J3 - 130 nm)	
Density		128 Mb, 256 Mb, 512 Mb, 1 Gb (For 32 Mb and 64 Mb, please refer to S29GL-N data sheet)		32 Mb, 64 Mb, 128 Mb, 256 Mb	
Package (Pinout Style)		56-Pin TSOP	(Infineon, 128 Mb to 1 Gb)	56-lead TSOP	(J3, 32 Mb to 256 Mb)
		64-ball Fortified BGA	(Infineon, 128 Mb to 1 Gb) 11 x 13 x 1.4 mm	64-ball Easy BGA	(J3, 32 Mb to 256 Mb) 10 x 13 x 1.2 mm
Operating Voltage Range	V_{CC} (Core)	3.0 - 3.6V, 2.7 - 3.6V		2.7 - 3.6V	
	V_{IO} (I/O)	1.65 - 3.6V		2.7 - 3.6	
Data Bus		x8/x16		x8/x16	
Sector Architecture		Uniform 128-KByte		Uniform 128-KByte	
Read	Asynchronous Initial Access	128 Mb: 90/100/110 ns 256 Mb: 90/100/110 ns 512 Mb: 100/110/120 ns 1 Gb: 110/120/130 ns		32-128 Mb: 75 ns 256 Mb: 95 ns	
	Asynchronous Page Access	25 ns (8 word)		25 ns (4/8 word)	
	Synchronous	NA		NA	
Program		15 μ s (32-Word Write Buffer - Per Word) 60 μ s (Single Word)		8 μ s (16-Word Write Buffer - Per Word) 40 μ s (Single Word)	
Erase		0.5 sec per sector		1.0 sec per sector	
Temperature Range		0°C to +70°C, -40°C to +85°C		-40°C to +85°C	

Feature Comparison

Table 2 Feature Comparisons between Infineon S29GL-P Flash Family and Numonyx StrataFlash Embedded Memory (P30 – 130 nm)

Feature		Product Specification			
		Infineon S29GL-P Flash Family		Numonyx StrataFlash Embedded Memory (P30 – 130 nm)	
Density		128 Mb, 256 Mb, 512 Mb, 1 Gb (For 64 Mb, please refer to 29GL-N datasheet)		64 Mb, 128 Mb, 256 Mb 512 Mb (2 x 256 Mb Die)	
Package (Pinout Style)		56-Pin TSOP	(Infineon, 128 Mb to 1 Gb)	56-lead TSOP	(P30, 64 Mb to 512 Mb)
		64-ball Fortified BGA	(Infineon, 128 Mb to 1 Gb) 11 x 13 x 1.4 mm	64-ball Easy BGA	10 x 13 x 1.2 mm (P30, 64 Mb to 256 Mb) 10 x 13 x 1.3 mm (P30, 512 Mb)
		NA		Quad+ SCSP	(P30, 512 Mb) 8 x 11 x 1.2mm (P30, 256 Mb) 8 x 11 x 1.0mm (P30, 64 Mb, 128 Mb) 8 x 10 x 1.2mm
Operating Voltage Range	V _{CC} (Core)	3.0 - 3.6V, 2.7 - 3.6V		1.7 - 2.0V	
	V _{IO} (I/O)	1.65 - 3.6V		1.7 - 3.6V	
Data Bus		x8/x16		x16	
Sector Architecture		Uniform 128-KByte		128-Kbyte (Main Blocks) 4 x 32-Kbyte (Parameter Blocks)	
Read	Asynchronous Initial Access	128 Mb: 90/100/110 ns 256 Mb: 90/100/110 ns 512 Mb: 100/110/120 ns 1 Gb: 110/120/130 ns		64-128 Mb: 85 ns 256-512 Mb: 88/95 ns	
	Asynchronous Page Access	25 ns (8 word)		25 ns (4/8 word)	
	Synchronous	NA		40 MHz	
Program		15 μs (32-Word Write Buffer - Per Word) 60 μs (Single Word)		13.8 μs (32-Word Write Buffer - Per Word) 90 μs (Single Word)	
Erase		0.5 sec per sector		1.2 sec per sector	
Temperature Range		0°C to +70°C, -40°C to +85°C		-40°C to +85°C	

Security Feature

3 Security Feature

Infineon S29GL-P Flash Family devices feature Advanced Sector Protection, which allows robust and complete user-defined security level. Infineon Advanced Sector Protection replaces less secure hardware lock-hard methods; and removes the possibility of hardware hacking, where secure data may be compromised with the application of either high or low voltage on certain flash pins.

Infineon Advanced Sector Protection also includes a unique Password Protection method, allowing an even higher level of security. The Password Protection Method is a highly sophisticated protection method that requires a 64-bit, user-defined password before any sectors can be unlocked.

Table 3 Security Comparisons between Infineon S29GL-P Flash Family and Numonyx Embedded Flash Memory (J3) and Numonyx StrataFlash Embedded Memory (P30)

Security Features	Infineon S29GL-P Flash Memory	Numonyx Embedded Flash Memory (J3)	Numonyx StrataFlash Embedded Memory (P30)
Software Locking and Unlocking of Individual Sectors	Infineon Advanced Sector Protection: Locking individual sector is allowed Unlocking individual sector is allowed Password Protection (optional feature) further increases sector protection	Locking individual block is allowed via software Unlocking individual block is not allowed. All locked blocks must be unlocked in parallel.	Locking individual block is allowed Unlocking individual block is not allowed. All locked blocks must be unlocked in parallel.
Hardware Protection	WP# locks highest or lowest sector (Infineon offers Advanced Sector Protection for even greater security)	VPEN = GND	WP# hardware locks any Locked-Down Blocks VPP = GND
OTP Space	128 Word Secure Silicon Region (Factory lock or customer lock option)	128 bit Protection Register (64 bit User Programmable) (64 bit Unique Device Identifier)	17 x 128 bit OTP Registers (64 bits programmed at Numonyx factory)
Additional Options	Password Protection	NA	4 optional OTP blocks in the main array

Package and Pinout

4 Package and Pinout

Infineon S29GL-P Flash Family devices allow flexibility between densities with seamless package and pinout offerings. Infineon S29GL-P is also pinout and package compatible to other Infineon flash families, such as the S29AL016J and S29GL-N. Contact your local Infineon representative or respective data sheets for further details.

By comparison, Numonyx devices vary package types and sizes as well as pinouts depending on density.

4.1 56 Pin TSOP Pinout Comparison

The 56-pin TSOP pinouts of Infineon and Numonyx are different. Migration from Numonyx products in 56-pin TSOP to the Infineon S29GL-P will require a board-level change.

Intel StrataFlash Embedded Memory (P30)	Intel StrataFlash Memory (J3)	Spansion S29GL-P Flash Family	Pin	Spansion S29GL-P Flash Family	Intel StrataFlash Memory (J3)	Intel StrataFlash Embedded Memory (P30)
A16	A22	A23	1	56	A24	WAIT
A15	CE1	A22	2	55	A25	A17
A14	A21	A15	3	54	A16	DQ15
A13	A20	A14	4	53	BYTE#	DQ7
A12	A19	A13	5	52	VSS	DQ14
A11	A18	A12	6	51	DQ15 /A-1	DQ6
A10	A17	A11	7	50	DQ7	DQ13
A9	A16	A10	8	49	DQ14	DQ5
A23	VCC	A9	9	48	DQ6	DQ12
A22	A15	A8	10	47	DQ13	DQ4
A21	A14	A19	11	46	DQ5	ADV#
VSS	A13	A20	12	45	DQ12	CLK
VCC	A12	WE#	13	44	DQ4	RST#
WE#	CEO	RESET#	14	43	VCC	VPP
WP#	VPEN	A21	15	42	DQ11	DQ11
A20	RP#	WP#/ACC	16	41	DQ3	DQ3
A19	A11	RY/BY#	17	40	DQ10	DQ10
A18	A10	A18	18	39	DQ2	DQ2
A8	A9	A17	19	38	DQ9	VCCQ
A7	A8	A7	20	37	DQ1	DQ9
A6	GND	A6	21	36	DQ8	DQ1
A5	A7	A5	22	35	DQ0	DQ8
A4	A6	A4	23	34	OE#	DQ0
A3	A5	A3	24	33	VSS	VCC
A2	A4	A2	25	32	CE#	OE#
A24	A3	A1	26	31	A0	VSS
A25	A2	NC	27	30	NC	CE#
VSS	A1	NC	28	29	VIO	VIO

Figure 1 56 Pin TSOP Pinout Comparisons between Infineon S29GL-P Flash Family and Numonyx Embedded Flash Memory (J3) and Numonyx StrataFlash Embedded Memory (P30)

Note:

For S29GL-P:

1. Pin 1 is NC on the S29GL128P.
2. Pin 56 is NC on the S29GL256P, and S29GL128P.
3. Pin 55 is NC on the S29GL512P, S29GL256P, and S29GL128P.

Package and Pinout

4.2 BGA Pinout Comparisons

Infineon offers Infineon pinout Fortified BGA which allows backwards and forward compatibility within the S29GL-P family as well as other Infineon flash families.

Easy BGA pinouts are different from Infineon's Fortified BGA packages. Migration from Easy BGA products to the Infineon S29GL-P will require a board-level change.

4.3 Infineon 64-ball Fortified BGA Pinout vs. J3 Easy BGA Pinout

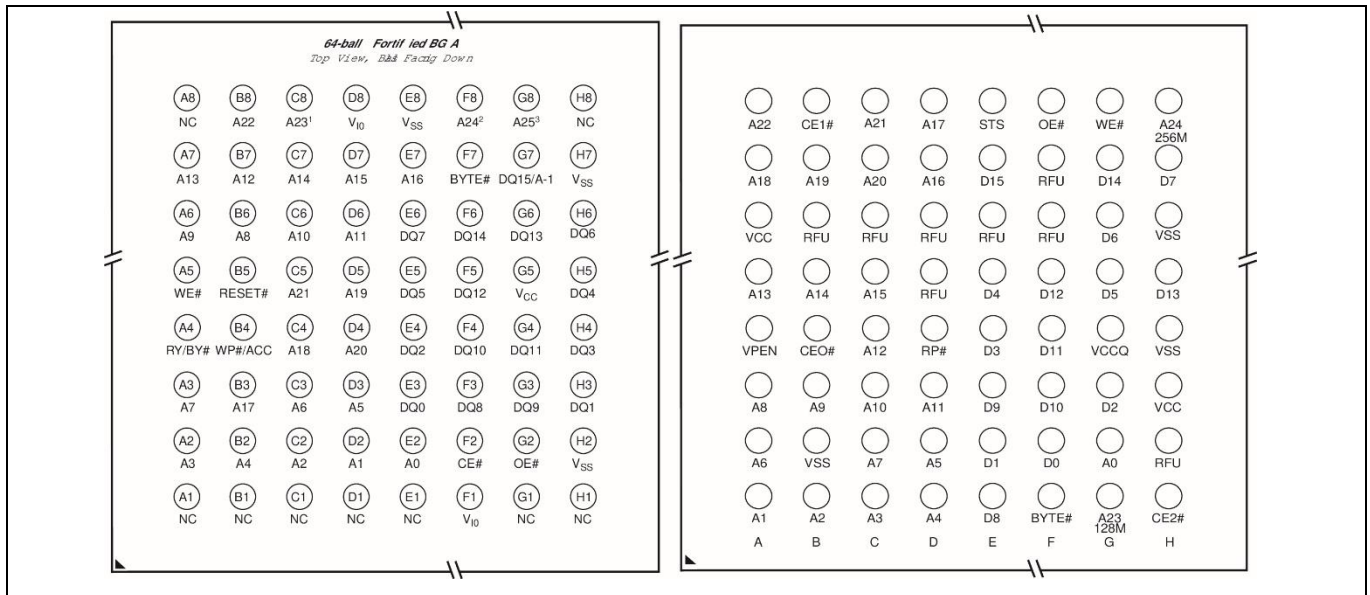


Figure 2 Infineon S29GL-P Fortified BGA (Left) vs Numonyx Embedded Flash Memory (J3 - 130 nm) Easy BGA (Right)

Note:

1. NC on S29GL128P.
2. NC on S29GL128P and S29GL256P.
3. NC on S29GL128P, S29GL256P and S29GL512P.

Table 4 Work-around to Convert from Numonyx Embedded Flash Memory (J3 - 130 nm) to Infineon S29GL-P

Infienon	Numonyx	Numonyx J3 Description	Work-Around
WP#/ACC	VPEN	V _{IH} enables erasing, programming or configuring lock-bits. With V _{IL} , memory contents cannot be altered.	Set the PPB Lock Bit. (Global Volatile Sector Protection Freeze Command)
CE#	CE0#	Chip enable activates the device.	N/A
N/A	CE1#	Chip enable activates the device. Selects multiple devices—can be tied to ground for single Flash.	N/A for single Flash device. PCB change required to support multiple Infineon Flash.
N/A	CE#2	Chip enable activates the device. Selects multiple devices—can be tied to ground for single Flash.	N/A for single Flash device. PCB change required to support multiple Infineon Flash.

Package and Pinout

Infineon	Numonyx	Numonyx J3 Description	Work-Around
RESET#	RP#	Reset/Power-Down Pin. V_{IL} resets and places the device in power-down mode. V_{IH} enables normal operation.	N/A
RY/BY#	STS	Provides the status of the device. In default mode, acts as RY/BY# signal. Can be configured to generate an interrupt when a program/erase operation is complete.	N/A if used as RY/BY#. No work-around available for interrupt.
DQ15/A-1	A0	Byte-Select Address is the lowest order bit in x8 mode. Not used in x16 mode.	
V_{IO}	VCCQ	I/O Power Supply supports 2.7 V-3.6V (tied to V_{CC}).	N/A: For Infineon model numbers 01 and 02.

4.4 Infineon 64-ball Fortified BGA Pinout vs. P30 Easy BGA Pinout

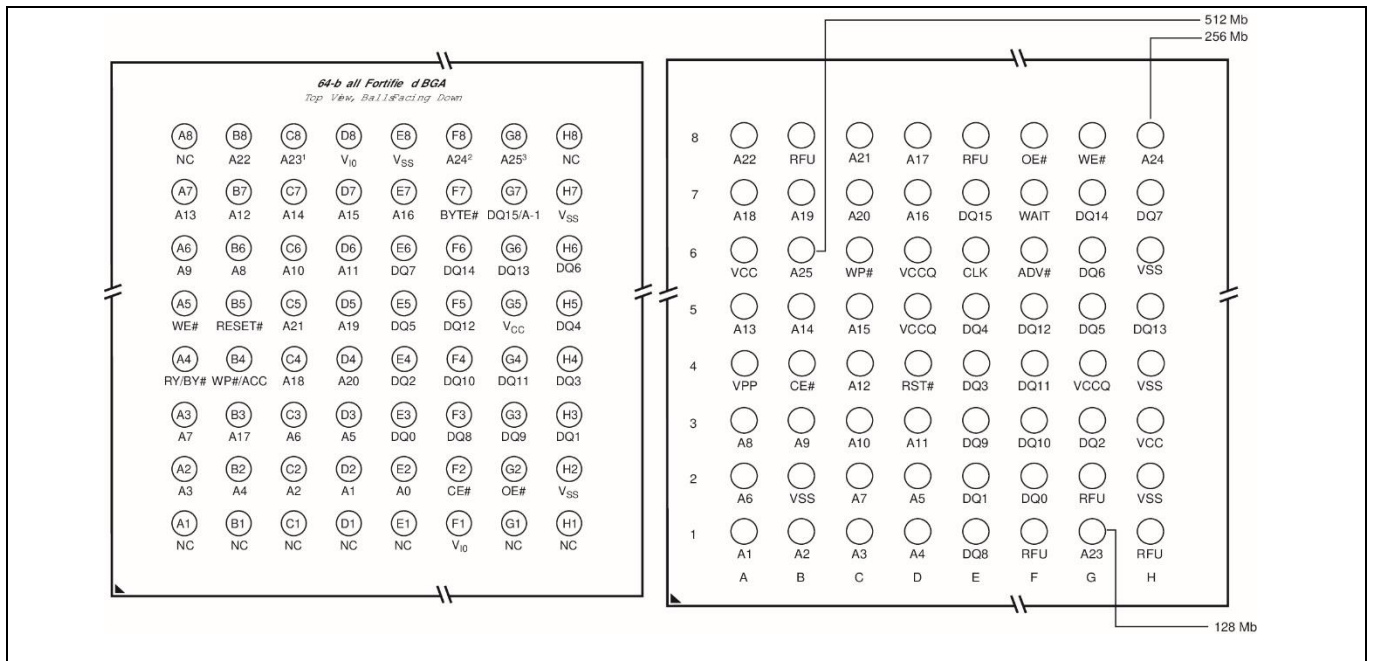


Figure 3 Infineon S29GL-P Fortified BGA (Left) vs Numonyx StrataFlash Embedded Memory (P30 – 130 nm) Easy BGA (Right)

Note:

1. NC on S29GL128P.
2. NC on S29GL128P and S29GL256P.
3. NC on S29GL128P, S29GL256P and S29GL512P.

Package and Pinout

Table 5 Work-around to Convert from Numonyx StrataFlash Embedded Memory (P30 - 130 nm) to Infineon S29GL-P

Infineon	Numonyx	Numonyx P30 Description	Work-Around
WP#/ACC	VPP	$V_{PP} = GND$ memory contents cannot be altered.	Set the PPB Lock Bit. (Global Volatile Sector Protection Freeze Command)
WP#/ACC	WP#	Hardware locks any Locked-Down Blocks	Infineon At V_{IL} , disables program and erase functions in the outermost sectors. Use Advance Sector Protection to lock and unlock any sectors
RESET#	RST#	Reset: V_{IL} resets and places the device. V_{IH} enables normal operation	N/A
V_{IO}	VCCQ	Output Power Supply	If I/O's need to be $<V_{CC}$, use Infineon model numbers V1 and V2.
N/A	CLK	Clock to synchronous operations	N/A
RY/BY#	N/A	Function not supported.	N/A
N/A	ADV#	I/O Power Supply supports 2.7V-3.6V (tied to V_{CC}).	N/A
N/A	WAIT	Address Valid: Address are latched on the rising edge of ADV# for synchronous operations	N/A
N/A	BYTE#	N/A	Drive BYTE# to V_{IH}

Software Support

5 Software Support

The J3 and P30 command sets are proprietary and will require SW redesign to an industry standard Flash command set.

Infineon is dedicated to providing customers with world-class technical service and support. To assist development of Infineon Flash memory, Infineon offers a full range of software and support tools which simplifies design and shorten time to market.

Infineon royalty free software tools include:

- Low Level Drivers (LLD)
- Enhanced Flash Driver (EFD)
- Data Management Software (DMS)
- Infineon File System (SSP)

For more information, ask your Infineon representative or visit the web site at <https://www.cypress.com/support/>.

Revision history

Revision history

Document version	Date of release	Description of changes
**	2010-07-01	Initial version
*A	2015-11-06	Updated in template
*B	2017-08-02	Updated logo and Copyright
*C	2018-07-09	Updated template
*D	2021-04-23	Updated to Infineon template

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